

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPP17N25S3-100	**Issued**	24. February 2022
MA#	MA005700102		
Package	PG-TO220-3-1	**Weight***	2037.37 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.114	0.20	0.20	2019	2019
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.04	40.09	400188	400709
wire	non noble metal	aluminium	7429-90-5	6.952	0.34	0.34	3412	3412
encapsulation	inorganic material	zincoxide	1314-13-2	5.942	0.29		2916	
	miscellaneous	miscellaneous	-	23.768	1.17		11666	
	plastics	epoxy resin	-	89.128	4.37		43747	
	inorganic material	silicondioxide	60676-86-0	475.351	23.33	29.16	233316	291645
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10534	10534
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.076			37	
	noble metal	silver	7440-22-4	0.095			46	
	non noble metal	lead	7439-92-1	3.613	0.18	0.18	1773	1856
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.93	28.97	289327	289704
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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